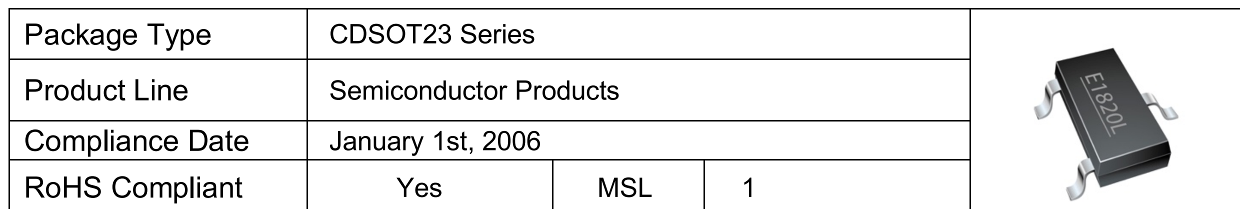
MATERIAL DECLARATION SHEET



Package Type	CDSOT23 Series		
Product Line	Semiconductor Products		
Compliance Date	January 1st, 2006		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.005271	Fused Silica (SiO2)	60676-86-0	87.70	47.10	53.71
				Epoxy resin	129915-35-1	5.00	2.69	
				Epoxy CN	29690-82-2	2.00	1.07	
				Phenol resin	9003-35-4	5.00	2.69	
				Carbon Black	1333-86-4	0.30	0.16	
2	Leadframe	Copper alloy	0.004021	Copper	7440-50-8	94.11	37.84	40.21
				Iron	7439-89-6	2.22	0.89	
				Zinc	7440-66-6	0.01	0.00	
				Phosphorous	7723-14-0	0.03	0.01	
				Silver (Plating)	7440-22-4	3.63	1.46	
3	Chip	Silicon	0.000402	Silicon	7440-21-3	93.73	3.77	4.02
				Aluminum	7429-90-5	3.05	0.12	
				Nickel	7440-02-0	3.08	0.12	
				Gold	7440-57-5	0.13	0.01	
4	Die Attach	Silver epoxy	0.000079	Silver	7440-22-4	75.00	0.59	0.79
				Epoxy	9003-36-5	25.00	0.20	
5	Bond wires	Gold	0.000044	Gold	7440-57-5	100.00	0.44	0.44
6	Terminal Finish	Matte Tin	0.000083	Matte Tin	7440-31-5	100.00	0.83	0.83
		Total Weight	0.010000					

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society